TRIACSSilicon Bidirectional Thyristors

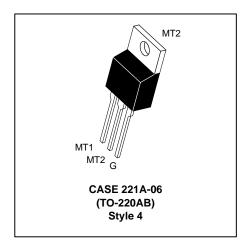
Designed for high performance full-wave ac control applications where high noise immunity and high commutating di/dt are required.

- Blocking Voltage to 800 Volts
- On-State Current Rating of 8.0 Amperes RMS at 100°C
- Uniform Gate Trigger Currents in Three Modes
- High Immunity to dv/dt 250 V/μs minimum at 125°C
- Minimizes Snubber Networks for Protection
- Industry Standard TO-220AB Package
- High Commutating di/dt 6.5 A/ms minimum at 125°C

MAC8 SERIES*

*Motorola preferred devices

TRIACS 8 AMPERES RMS 400 thru 800 VOLTS



MAXIMUM RATINGS (T_J = 25° C unless otherwise noted)

Symbol	Parameter	Value	Unit	
VDRM	Peak Repetitive Off-State Voltage (1) (-40 to 125°C, Sine Wave, 50 to 60 Hz, Gate Open)	MAC8D MAC8M MAC8N	400 600 800	Volts
I _{T(RMS)}	On-State RMS Current (60 Hz, T _C = 100°C)		8.0	А
ITSM	Peak Non-repetitive Surge Current (One Full Cycle, 60 Hz, T _J = 125°C)		80	А
I ² t	Circuit Fusing Consideration (t = 8.3 ms)		26	A ² sec
PGM	Peak Gate Power (Pulse Width ≤ 1.0 μs, T _C = 80°C)		16	Watts
PG(AV)	Average Gate Power (t = 8.3 ms, T _C = 80°C)		0.35	Watts
TJ	Operating Junction Temperature Range		-40 to +125	°C
T _{stg}	Storage Temperature Range		-40 to +150	°C

THERMAL CHARACTERISTICS

	R _θ JC R _θ JA	Thermal Resistance — Junction to Case — Junction to Ambient	2.2 62.5	°C/W
Γ	TL	Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds	260	°C

⁽¹⁾ V_{DRM} for all types can be applied on a continuous basis. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

Preferred devices are Motorola recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted)

Symbol	Characteristic		Min	Тур	Max	Unit
OFF CHA	RACTERISTICS					•
I _{DRM}	Peak Repetitive Blocking Current (VD = Rated VDRM, Gate Open)	T _J = 25°C T _J = 125°C	_ _	_ _	0.01 2.0	mA
ON CHAR	ACTERISTICS				•	•
V _{TM}	Peak On-State Voltage* (I _{TM} = ±11 A Peak)		_	1.2	1.6	Volts
I _{GT}	Continuous Gate Trigger Current (V_D = 12 V, R_L = 100 Ω) MT2(+), G(+) MT2(+), G(-) MT2(-), G(-)		5.0 5.0 5.0	13 16 18	35 35 35	mA
lΗ	Hold Current (V _D = 12 V, Gate Open, Initiating Current = ±150 mA)		_	20	40	mA
ΙL	Latch Current (V _D = 24 V, I _G = 35 mA) MT2(+), G(+); MT2(-), G(-) MT2(+), G(-)		_ _ _	20 30	50 80	mA
V _{GT}	Gate Trigger Voltage (V _D = 12 V, R _L = 100 Ω) MT2(+), G(+) MT2(+), G(-) MT2(-), G(-)		0.5 0.5 0.5	0.69 0.77 0.72	1.5 1.5 1.5	Volts
DYNAMIC	CHARACTERISTICS					
(di/dt) _C	Rate of Change of Commutating Current* See Figure 10. (V _D = 400 V, I _{TM} = 4.4 A, Commutating dv/dt = 18 V/µs, Gate Open, T _J = 125°C, f = 250 Hz, No Snubber)	C _L = 10 μF L _L = 40 mH	6.5	_	_	A/ms
dv/dt	Critical Rate of Rise of Off-State Voltage (VD = Rated VDRM, Exponential Waveform, Gate Open, TJ	= 125°C)	250	_	_	V/μs

^{*}Indicates Pulse Test: Pulse Width ≤ 2.0 ms, Duty Cycle ≤ 2%.

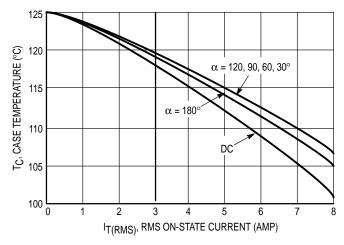


Figure 1. RMS Current Derating

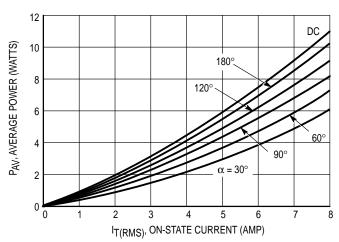


Figure 2. On-State Power Dissipation

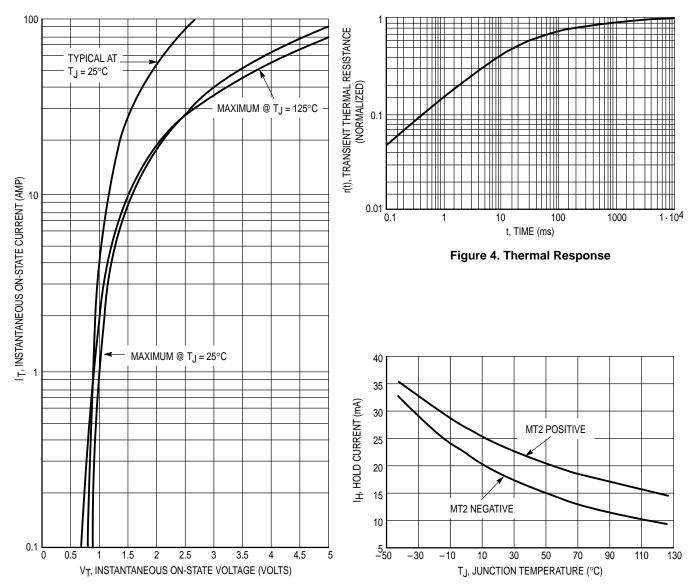


Figure 3. On-State Characteristics

Figure 5. Hold Current Variation

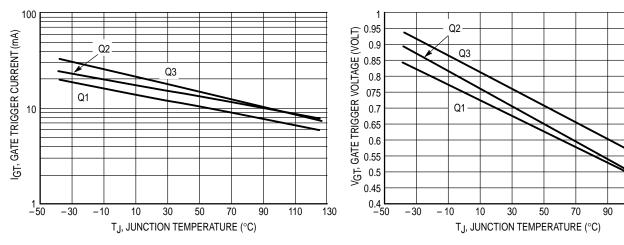


Figure 6. Gate Trigger Current Variation

Figure 7. Gate Trigger Voltage Variation

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MAC8 SERIES

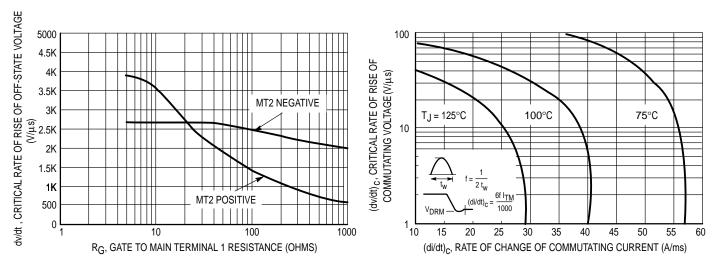


Figure 8. Critical Rate of Rise of Off-State Voltage (Exponential)

Figure 9. Critical Rate of Rise of Commutating Voltage

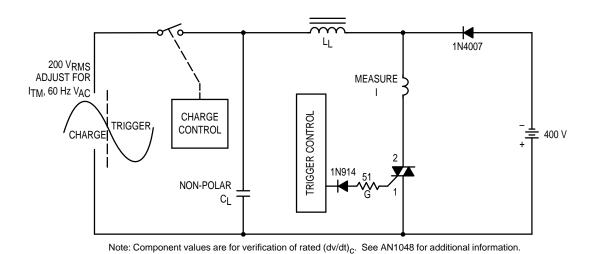


Figure 10. Simplified Test Circuit to Measure the Critical Rate of Rise of Commutating Voltage